# Let us share a bit "More than Moore"





AM is becoming increasingly important, especially for 3D electronics concepts. New 3D printing processes enable heterogeneous and functional integration through multi-hybrid and tool-free production. Both, physical and/or electrical functions, can be printed, additionally, electronic components can be assembled within a single operation.

With the new 3D printing processes, multidimensional substrates (components) and circuit carriers with integrated functions such as sensors, actuators, and electro-optical or bionic properties can be realized, without the need for a carrier substrate or already manufactured Printed Circuit Board.

# Get in Touch with 3D Electronics

together with



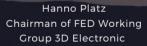
#### **CONTACT US**

Fachverband Elektronikdesign und -fertigung e. V. Frankfurter Allee 73c D - 10247 Berlin Tel: +49 (0)30 340 6030 - 50 Fax: +49 (0)30 340 6030 - 61 seminare@fed.de

www.fed.de











Michael Matthes Deputy Chairman of FED Working Group 3D Electronic



# WORKING GROUP FOR 3D ELECTRONICS





We connect

# **3D ELECTRONICS WORKING GROUP**



Our mission is to collect and evaluate



# **OUR VISION**



#### Motivation

3D electronics is an important key to innovative and efficient electronic solutions. New construction and connection technologies (AVT) enable multifunctional integration of sensors, actuators and electronics.

### New possibilities

- New formfactors
- Improve performance
- Increase functional integration

## White Paper for "AME Classification"

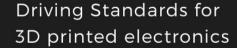
- Introduction to 3D Electronics
- AME Class 1 Class 5
- Design Tools for 3D Electronics



And the Community For 3D Printed Electronics J.A.M.E.S establishing the first online Community for 3D printed electronics, with which all individuals and organizations can share the latest trends, news and designs for 3D printed electronics and additively manufactured electronics.







by Joining forces with IPC



